



General Description

The AOTF10N50FD has been fabricated using an advanced high voltage MOSFET process that is designed to deliver high levels of performance and robustness in popular AC-DC applications. By providing low $R_{DS(on)}$, C_{iss} and C_{rss} along with guaranteed avalanche capability this part can be adopted quickly into new and existing offline power supply designs.

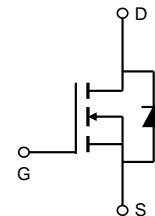
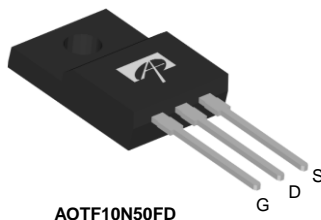
Product Summary

V_{DS}	600V@150°C
I_D (at $V_{GS}=10V$)	10A
$R_{DS(on)}$ (at $V_{GS}=10V$)	< 0.75Ω

100% UIS Tested
100% R_g Tested



Top View
TO-220F



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	AOTF10N50FD	Units
Drain-Source Voltage	V_{DS}	500	V
Gate-Source Voltage	V_{GS}	±30	V
Continuous Drain Current	I_D	$T_C=25^\circ C$	10*
		$T_C=100^\circ C$	6*
Pulsed Drain Current ^c	I_{DM}	33	A
Avalanche Current ^c	I_{AR}	3.8	A
Repetitive avalanche energy ^c	E_{AR}	216	mJ
Single pulsed avalanche energy ^g	E_{AS}	433	mJ
Peak diode recovery dv/dt	dv/dt	5	V/ns
Power Dissipation ^b	P_D	$T_C=25^\circ C$	50
		Derate above 25°C	0.4
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C
Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	T_L	300	°C

Thermal Characteristics

Parameter	Symbol	AOTF10N50FD	Units
Maximum Junction-to-Ambient ^{a,d}	$R_{\theta JA}$	65	°C/W
Maximum Junction-to-Case	$R_{\theta JC}$	2.5	°C/W

* Drain current limited by maximum junction temperature.

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =10mA, V _{GS} =0V, T _J =25°C I _D =10mA, V _{GS} =0V, T _J =150°C	500		600	V
BV _{DSS} /ΔT _J	Breakdown Voltage Temperature Coefficient	I _D =10mA, V _{GS} =0V		0.56		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =500V, V _{GS} =0V V _{DS} =400V, T _J =125°C			10 100	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±30V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =5V, I _D =250μA	2.5	3.1	4.2	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =5A		0.6	0.75	Ω
g _{FS}	Forward Transconductance	V _{DS} =40V, I _D =5A		10		S
V _{SD}	Diode Forward Voltage	I _S =10A, V _{GS} =0V		0.93	1.6	V
I _S	Maximum Body-Diode Continuous Current				10	A
I _{SM}	Maximum Body-Diode Pulsed Current				33	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =25V, f=1MHz	820	1030	1240	pF
C _{oss}	Output Capacitance		75	112	150	pF
C _{riss}	Reverse Transfer Capacitance		5	10	15	pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	1.7	3.4	5.2	Ω
SWITCHING PARAMETERS						
Q _g	Total Gate Charge	V _{GS} =10V, V _{DS} =400V, I _D =10A	20	26	35	nC
Q _{gs}	Gate Source Charge			4.8		nC
Q _{gd}	Gate Drain Charge			9.5		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =250V, I _D =10A, R _G =25Ω		24		ns
t _r	Turn-On Rise Time			65		ns
t _{D(off)}	Turn-Off DelayTime			69		ns
t _f	Turn-Off Fall Time			50		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =10A, dI/dt=100A/μs, V _{DS} =100V		116	190	ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =10A, dI/dt=100A/μs, V _{DS} =100V		0.3	0.6	μC

- A. The value of R_{θJA} is measured with the device in a still air environment with T_A=25° C.
- B. The power dissipation P_D is based on T_{J(MAX)}=150° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
- C. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150° C, Ratings are based on low frequency and duty cycles to keep initial T_J=25° C.
- D. The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.
- E. The static characteristics in Figures 1 to 6 are obtained using <300 μs pulses, duty cycle 0.5% max.
- F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=150° C. The SOA curve provides a single pulse rating.
- G. L=60mH, I_{AS}=3.8A, V_{DD}=150V, R_G=25Ω, Starting T_J=25° C

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

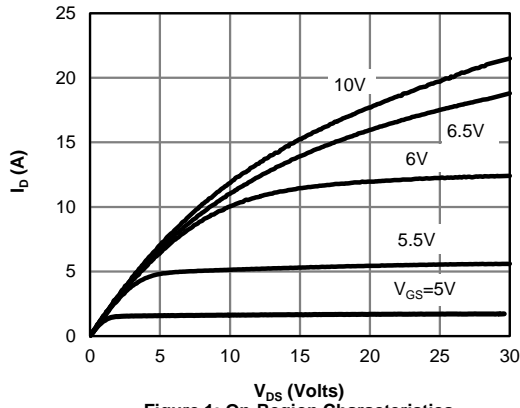


Figure 1: On-Region Characteristics

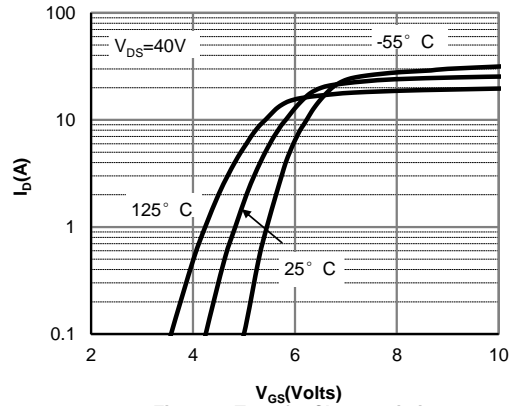


Figure 2: Transfer Characteristics

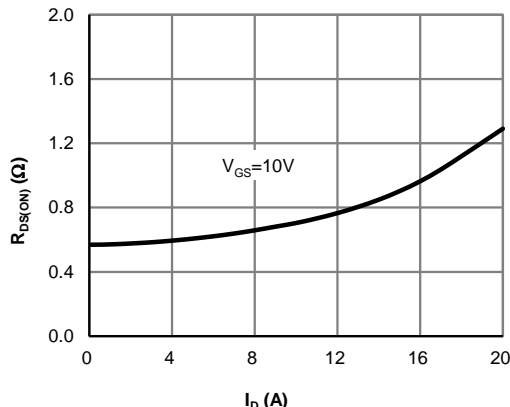


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

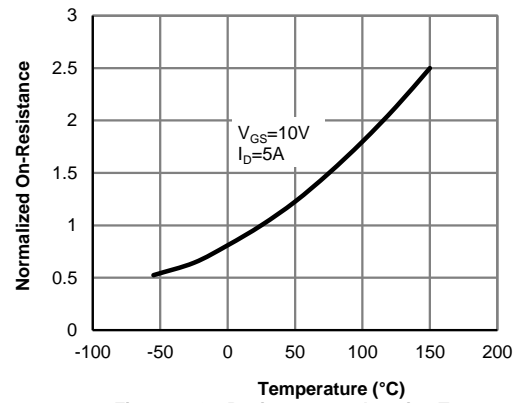


Figure 4: On-Resistance vs. Junction Temperature

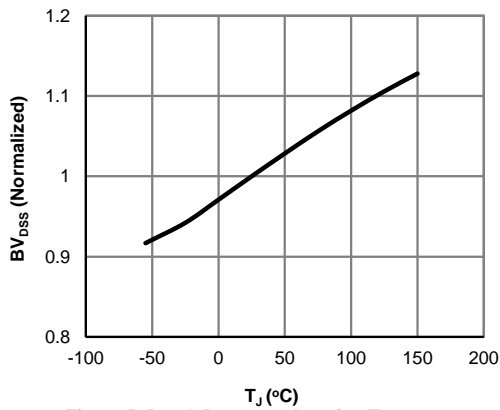


Figure 5: Break Down vs. Junction Temperature

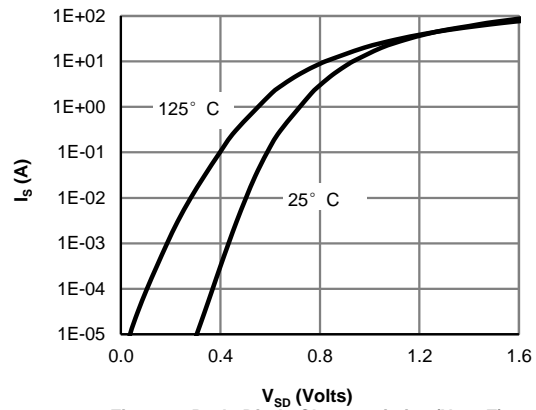


Figure 6: Body-Diode Characteristics (Note E)

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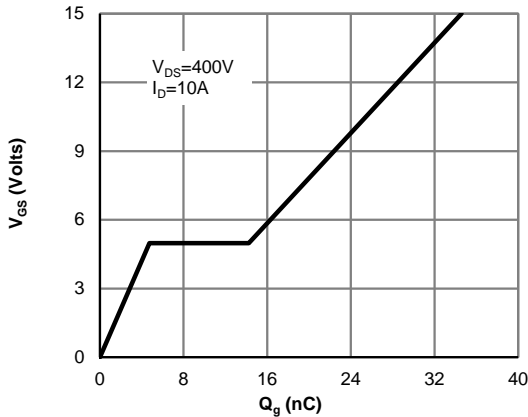


Figure 7: Gate-Charge Characteristics

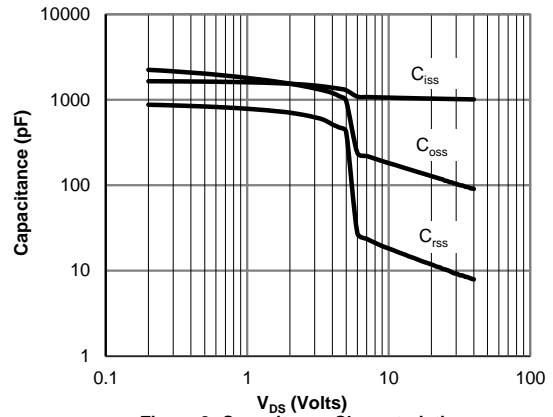


Figure 8: Capacitance Characteristics

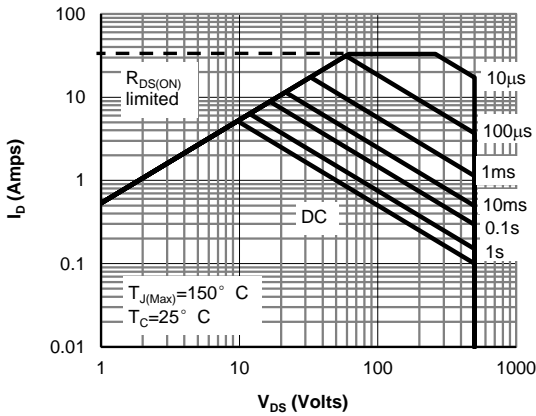


Figure 9: Maximum Forward Biased Safe Operating Area for AOTF10N50FD (Note F)

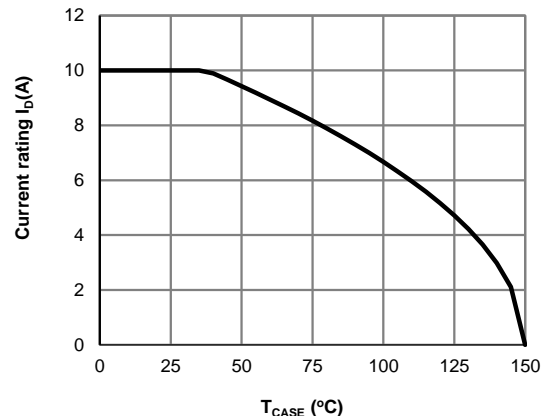


Figure 10: Current De-rating (Note B)

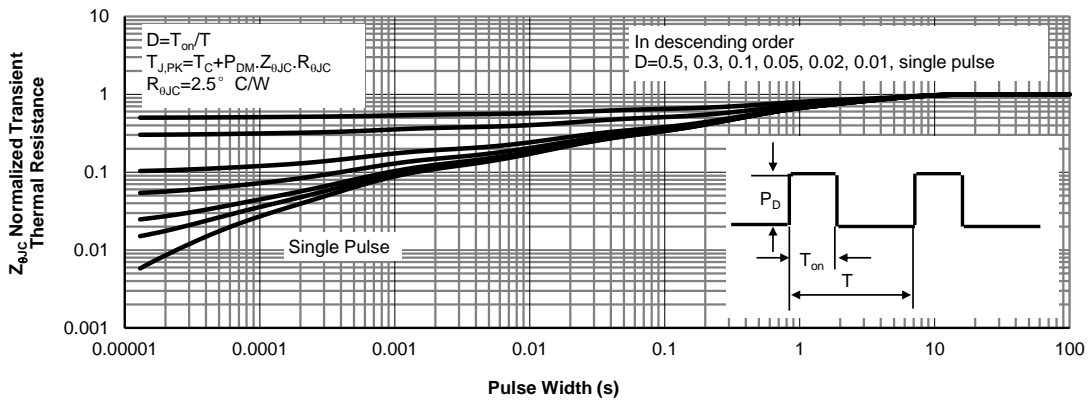


Figure 11: Normalized Maximum Transient Thermal Impedance for AOTF10N50FD (Note F)

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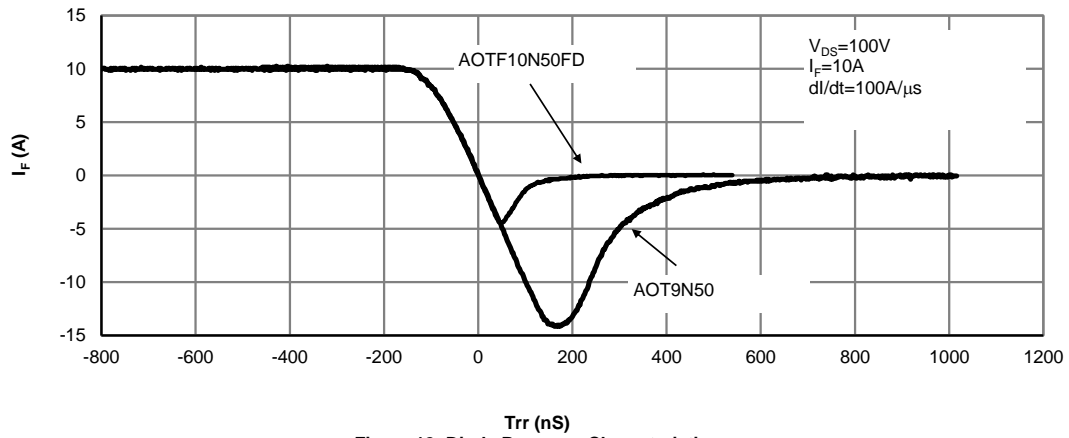
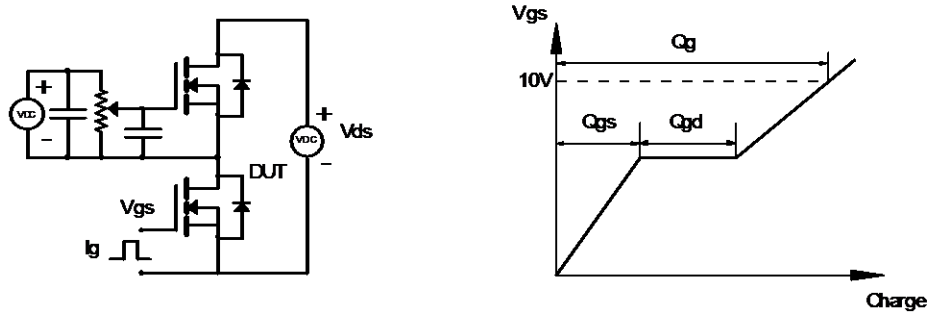
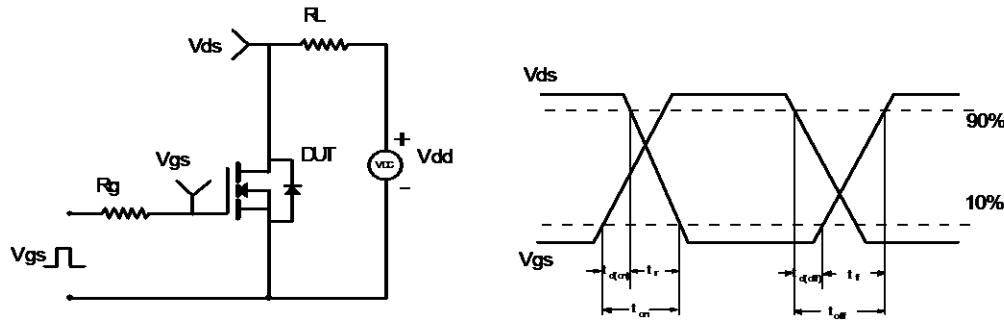


Figure 12: Diode Recovery Characteristics

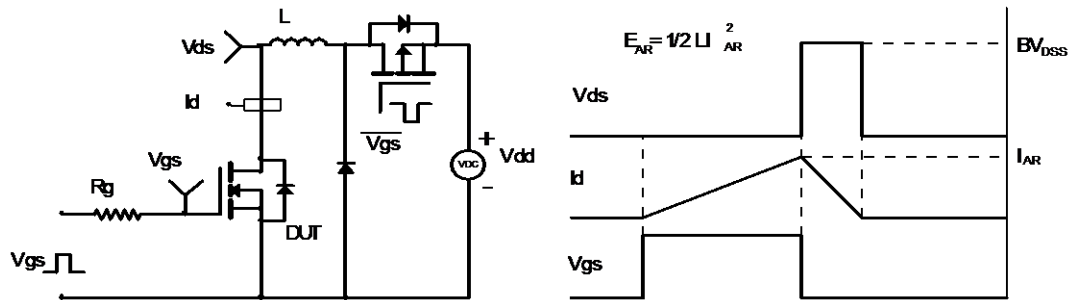
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

